



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-02-09
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8HRH*TWB018G	A	9941	2017-02-09
Amount	UoM	Unit type	ST ECOPACK Grade	
400.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
RAD	6.5-10.17-3.24	2	Through hole	
Comment	Package: DO 15 - MDF valid for CPs: BZW06-15B and P6KE18CA			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	die backside metal	28
Lead	1.66	soft solder	4145

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8HRH*TWB018G					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.820	mg	supplier	die	Silicon (Si)	7440-21-3		1.788	mg	982427	4473
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	2746	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	3844	18
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.007	mg	3844	18
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1098	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	6041	28
Leadframe	Copper & its alloys	286.215	mg	supplier	alloy	Copper (Cu)	7440-50-8		278.916	mg	974498	697290
				supplier	alloy	Iron (Fe)	7439-89-6		6.560	mg	22920	16400
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.395	mg	1380	988
				supplier	alloy	Zinc (Zn)	7440-66-6		0.344	mg	1202	860
Soft solder	Solder	1.793	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.658	mg	924707	4145
				supplier	solder	Tin (Sn)	7440-31-5		0.045	mg	25098	113
				supplier	solder	Silver (Ag)	7440-22-4		0.090	mg	50195	225
Encapsulation	Other Organic Materials	103.496	mg	supplier	mold compound	Quartz	14808-60-7		80.726	mg	779991	201815
				supplier	mold compound	epoxy resin	29690-82-2		15.007	mg	145001	37511
				supplier	mold compound	phenol resin	9003-35-4		7.245	mg	70003	18113
				supplier	mold compound	Carbon Black	1333-86-4		0.518	mg	5005	1295
Connections coating	Solder	6.676	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.676	mg	1000000	16690